Electronic Patent Application Fee Transmittal							
Application Number:	10537416						
Filing Date:	02-Jun-2005						
Title of Invention:	CONNECTION STRUCTURE FOR COAXIAL CONNECTOR AND MULTILAYER SUBSTRATE						
First Named Inventor/Applicant Name:	Haruhiko Hieda						
Filer:	Marvin Jay Spivak/Slobodanka Alic						
Attorney Docket Number:	273258US2PCT						
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Utility Appl issue fee		1501	1	1510	1510		
Publ. Fee- early, voluntary, or normal		1504	1	300	300		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
	Total in USD (\$)			1810